

co-pending U.S. Application Serial No. 09/283,024, filed March 30, 1999, entitled "Method
And Apparatus For Forming An Electric Contact With A Semiconductor Substrate",
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commonly owned by the assignee of the present invention, the contents of which are
expressly incorporated herein by reference.

IN THE CLAIMS

Kindly cancel claims 1-19, 28, 29, and 34-39.